

L1: TOP CONDUCTOR - COPPER 2.7 MIL
* PRE-PREG- FR-4 11.6 MIL
L2: IN1 CONDUCTOR - COPPER 2.7 MIL

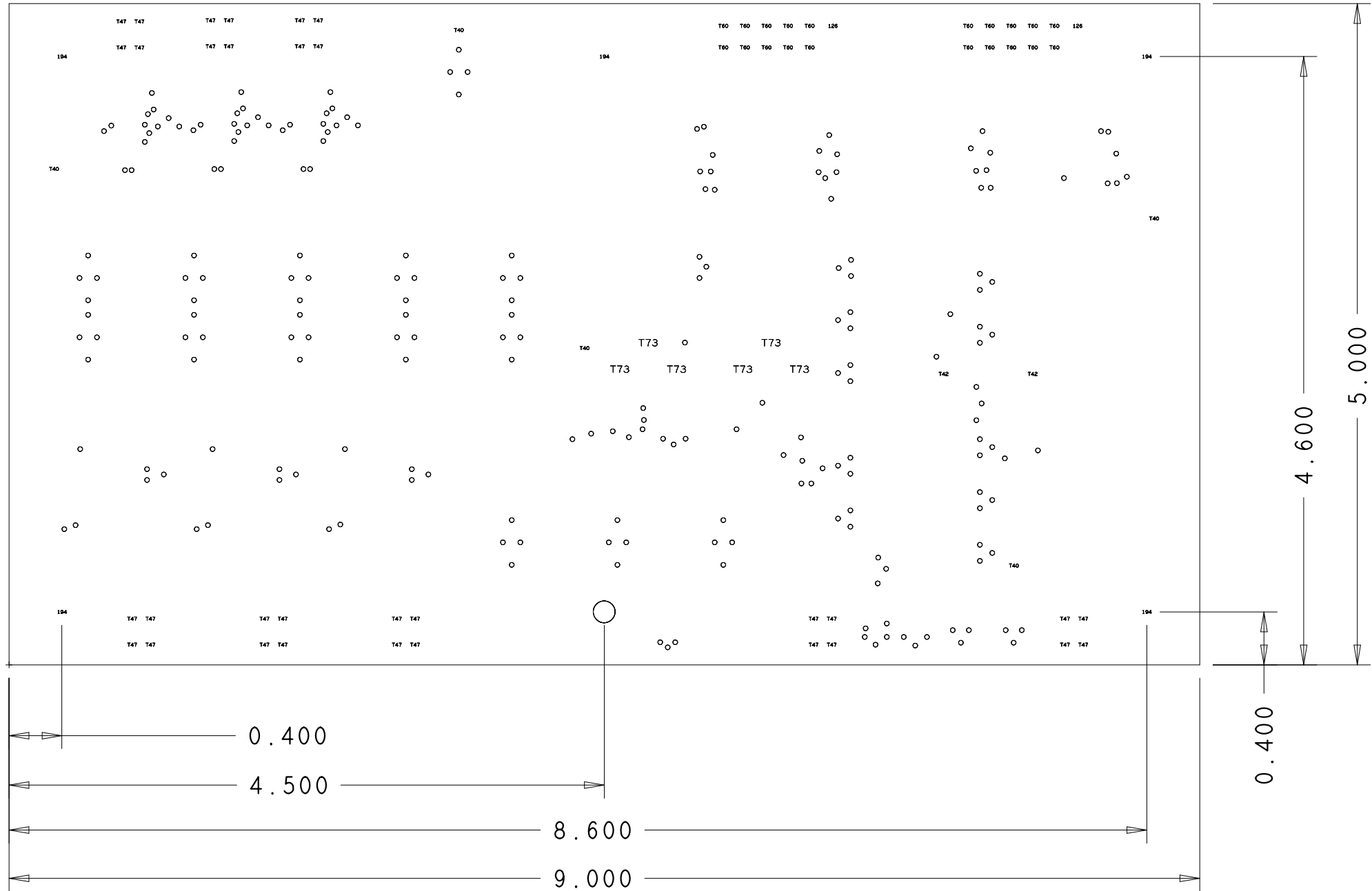
* CORE - FR-4 59 MIL

L3: IN2 CONDUCTOR - COPPER 2.7 MIL
* PRE-PREG - FR-4 11.6 MIL
L4: BOTTOM CONDUCTOR - COPPER 2.7 MIL

DESIGN CROSS SECTION CHART
TOTAL THICKNESS 93 MIL

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:
 - a. FR408 PER IPC 4101B/24 /26, OR /28.
 - b. SIGNAL LAYERS TO BE 2 OZ. COPPER.
 - c. PLANE LAYERS TO BE 2 OZ. COPPER.
 - d. OVERALL THICKNESS TO BE 0.093" +/- 10%
4. LEGEND:
 - a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:
 - a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR VIOLET, BOTH SIDES.
6. PLATING FINISH:
 - a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
 - ~~b. IMMERSION SOLDERING (ISg).~~
7. PROCESS ALLOWANCES:
 - a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH
 - b. HOLE DIMENSIONS APPLY AFTER PLATING.
 - c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION
 - d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003"
 - e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
 - f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
 - g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
○	15.0	PLATED	220
T40	40.0	PLATED	5
T42	42.0	PLATED	2
T47	47.0	PLATED	32
T60	60.0	PLATED	20
T73	73.0	PLATED	6
○	169.3	PLATED	1
T26	126.0	NON-PLATED	2
T24	194.0	NON-PLATED	5

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CCE BATTERY POWER MANAGEMENT PCB			
			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT RD MOSS LANDING, CA 95039			
DESIGNED BY: MARK CHAFFEY			SIZE C	RELEASE A	DWG NO 10021142-05/06-B	
LAYOUT BY: JOSE ROSAL			SCALE 1-1		SHEET	1-1